MAXIMUM RATINGS

Symbol	Characteristics	Value	Units
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V
VI	DC Input Voltage	$-0.5 \le V_{l} \le +7.0$	V
Vo	DC Output Voltage Output in Z or LOW State (Note 1)	$-0.5 \le V_0 \le +7.0$	٧
I _{IK}	DC Input Diode Current VI < GND	-50	mA
I _{OK}	DC Output Diode Current V _O < GND	-50	mA
Io	DC Output Sink Current	±50	mA
I _{CC}	DC Supply Current per Supply Pin	±100	mA
I _{GND}	DC Ground Current per Ground Pin	±100	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
P_{D}	Power Dissipation in Still Air SC-88, TSOP-6	200	mW
$\theta_{\sf JA}$	Thermal Resistance SC-88, TSOP-6	333	°C/W
TL	Lead Temperature, 1 mm from case for 10 s	260	°C
TJ	Junction Temperature under Bias	+150	°C
I _{Latchup}	Latchup Performance Above V _{CC} and Below GND at 85°C (Note 5)	±500	mA
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Classification Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 N/A	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- I_O absolute maximum rating must be observed.
 Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.
- 3. Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A
- 5. Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Units
V _{CC}	Supply Voltage Operating Data Retention Only	1.65 1.5	5.5 5.5	V
VI	Input Voltage	0	5.5	V
V _O	Output Voltage (Z or LOW State)	0	5.5	V
T _A	Operating Free-Air Temperature	-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $V_{CC} = 3.0 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0 0	20 10 5	ns/V

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	Ţ	T _A = 25°C			-55°C ≤ T _A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
V _{IH}	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V _{CC} 0.7 V _{CC}			0.75 V _{CC} 0.7 V _{CC}		V
V _{IL}	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V _{CC} 0.3 V _{CC}		0.25 V _{CC} 0.3 V _{CC}	V
I _{LKG}	Z-State Output Leakage Current	$V_{IN} = V_{IL}$ $V_{OUT} = V_{CC}$ or GND	2.3 to 5.5			±5.0		±10.0	μΑ
V _{OL}	Low-Level Output	I _{OL} = 100 μA	1.65 to 5.5		0.0	0.1		0.1	V
	Voltage V _{IN} = V _{IL}	I _{OL} = 4 mA	1.65		0.08	0.24		0.24	
		I _{OL} = 8 mA	2.3		0.20	0.3		0.3	
		I _{OL} = 12 mA	2.7		0.22	0.4		0.4	
		I _{OL} = 16 mA	3.0		0.28	0.4		0.4	
		I _{OL} = 24 mA	3.0		0.38	0.55		0.55	
		I _{OL} = 32 mA	4.5		0.42	0.55		0.55	
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	0 to 5.5			±0.1		±1.0	μА
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0			1		10	μΑ
Icc	Quiescent Supply Current	V _{IN} = 5.5 V or GND	5.5			1		10	μΑ

AC ELECTRICAL CHARACTERISTICS t_R = t_F = 2.5 ns; C_L = 50 pF; R_L = 500 Ω

				T _A = 25°C		-55°C ≤ T	_A ≤ 125°C		
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Units
t _{PZL}		$R_L = R_1 = 5000 \Omega, C_L = 15 pF$	1.8 ± 0.15	1.8	5.3	11.5	1.8	12.0	ns
(Figure 3 and 4)		$R_L = R_1 = 500 \Omega, C_L = 50 pF$	2.5 ± 0.2	1.2	3.7	5.8	1.2	6.4	
			3.3 ± 0.3	0.8	2.9	4.4	0.8	4.8	
			5.0 ± 0.5	0.5	2.3	3.5	0.5	3.9	
t _{PLZ}	Propagation Delay	$R_L = R_1 = 5000 \Omega, C_L = 15 pF$	1.8 ± 0.15	1.8	5.3	11.5	1.8	12.0	ns
	(Figure 3 and 4)		2.5 ± 0.2	1.2	2.8	5.8	1.2	6.4	
		$R_L = R_1 = 500 \Omega, C_L = 50 pF$	3.3 ± 0.3	0.8	2.1	4.4	0.8	4.8	
			5.0 ± 0.5	0.5	1.4	3.5	0.5	3.9	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	2.5	pF
C _{OUT}	Output Capacitance	V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	4.0	pF
C _{PD}	Power Dissipation Capacitance (Note 6)	10 MHz, V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	4.0	pF

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

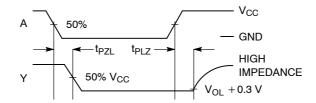
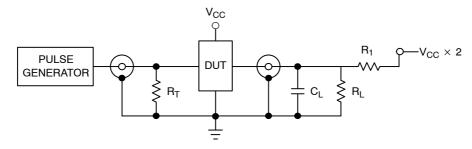


Figure 3. Switching Waveforms



 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

ORDERING INFORMATION

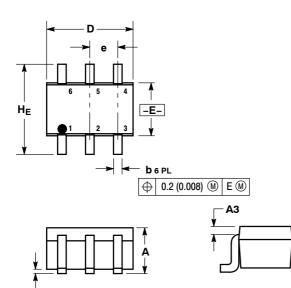
Device	Package	Shipping [†]
NL27WZ07DFT2G	SC-88 / SOT-363 / SC-70-6 (Pb-Free)	3000 / Tape & Reel
NLV27WZ07DFT2G*	SC-88 / SOT-363 / SC-70-6 (Pb-Free)	3000 / Tape & Reel
NL27WZ07DTT1G	TSOP-6 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

PACKAGE DIMENSIONS

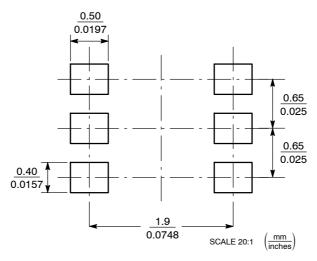
SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE W**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

	MILLIMETERS				INCHES	3
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.95	1.10	0.031	0.037	0.043
A 1	0.00	0.05	0.10	0.000	0.002	0.004
А3	0.20 REF 0.008 RE			≣F		
b	0.10	0.21	0.30	0.004	0.008	0.012
C	0.10	0.14	0.25	0.004	0.005	0.010
D	1.80	2.00	2.20	0.070	0.078	0.086
Е	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65 BSC			0	.026 BS	С
L	0.10	0.20	0.30	0.004	0.008	0.012
He	2.00	2 10	2 20	0.078	0.082	0.086

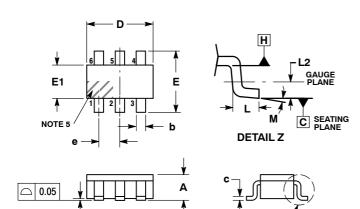
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

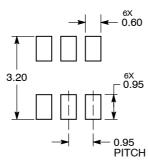
TSOP-6 CASE 318G-02 **ISSUE U**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM
- LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
 PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H. PIN ONE INDICATOR MUST BE LOCATED IN THE INDICATED ZONE.

	MILLIMETERS					
DIM	MIN	NOM	MAX			
Α	0.90	1.00	1.10			
A1	0.01	0.06	0.10			
b	0.25	0.38	0.50			
С	0.10	0.18	0.26			
D	2.90	3.00	3.10			
E	2.50	2.75	3.00			
E1	1.30	1.50	1.70			
е	0.85	0.95	1.05			
L	0.20	0.40	0.60			
L2	0.25 BSC					
M	0°	-	10°			

RECOMMENDED **SOLDERING FOOTPRINT***



DIMENSIONS: MILLIMETERS

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